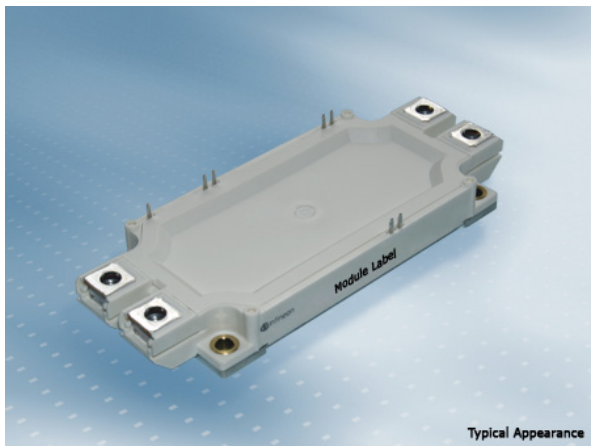


EconoDUAL™3 モジュール 高速トレンチ/フィールドストップ IGBT3 and エミッターコントロール3 diode内蔵 and NTCサーミスタ

EconoDUAL™3 module with Trench/Fieldstop IGBT3 and Emitter Controlled 3 diode and NTC



$V_{CES} = 600V$   
 $I_{C\ nom} = 600A / I_{CRM} = 1200A$

**一般応用**

- ハイパワーコンバータ
- モーター駆動
- サーボ駆動
- UPSシステム
- 風力タービン

**電気的特性**

- トレンチ IGBT 3
- $T_{vj\ op} = 150^{\circ}C$
- 正温度特性を持った  $V_{CESat}$  飽和電圧

**機械的特性**

- 高いパワー密度
- 絶縁されたベースプレート
- 標準ハウジング

**Typical Applications**

- High Power Converters
- Motor Drives
- Servo Drives
- UPS Systems
- Wind Turbines

**Electrical Features**

- Trench IGBT 3
- $T_{vj\ op} = 150^{\circ}C$
- $V_{CESat}$  with positive Temperature Coefficient

**Mechanical Features**

- High Power Density
- Isolated Base Plate
- Standard Housing

**Module Label Code**

Barcode Code 128



DMX - Code



**Content of the Code**

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

prepared by: CU	date of publication: 2013-11-04	
approved by: MK	revision: 3.1	UL approved (E83335)



**IGBT- インバータ / IGBT, Inverter**  
**最大定格 / Maximum Rated Values**

コレクタ・エミッタ間電圧 Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	600	V
連続DCコレクタ電流 Continuous DC collector current	$T_C = 55^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$ $T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$ $I_C$	600 700	A A
繰り返しピークコレクタ電流 Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	1200	A
トータル損失 Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$P_{\text{tot}}$	1650	W
ゲート・エミッタ間ピーク電圧 Gate-emitter peak voltage		$V_{GES}$	+/-20	V

**電気的特性 / Characteristic Values**

			min.	typ.	max.		
コレクタ・エミッタ間飽和電圧 Collector-emitter saturation voltage	$I_C = 600\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 600\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 600\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,45 1,60 1,70	1,90	V V V	
ゲート・エミッタ間しきい値電圧 Gate threshold voltage	$I_C = 9,60\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{GEth}$	4,9	5,8	6,5	V
ゲート電荷量 Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		$Q_G$	6,50			$\mu\text{C}$
内蔵ゲート抵抗 Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{Gint}$	0,68			$\Omega$
入力容量 Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{ies}$	39,0			nF
帰還容量 Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{res}$	1,15			nF
コレクタ・エミッタ間遮断電流 Collector-emitter cut-off current	$V_{CE} = 600\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{CES}$			5,0	mA
ゲート・エミッタ間漏れ電流 Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{GES}$			400	nA
ターンオン遅れ時間 (誘導負荷) Turn-on delay time, inductive load	$I_C = 600\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 2,4\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{don}$	0,10 0,11 0,12			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
ターンオン上昇時間 (誘導負荷) Rise time, inductive load	$I_C = 600\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 2,4\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$	0,09 0,095 0,10			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
ターンオフ遅れ時間 (誘導負荷) Turn-off delay time, inductive load	$I_C = 600\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 2,4\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{doff}$	0,67 0,71 0,73			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
ターンオフ下降時間 (誘導負荷) Fall time, inductive load	$I_C = 600\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 2,4\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$	0,07 0,075 0,075			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
ターンオンスイッチング損失 Turn-on energy loss per pulse	$I_C = 600\text{ A}, V_{CE} = 300\text{ V}, L_S = 30\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 6000\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 2,4\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$	8,90 9,90 10,5			mJ mJ mJ
ターンオフスイッチング損失 Turn-off energy loss per pulse	$I_C = 600\text{ A}, V_{CE} = 300\text{ V}, L_S = 30\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 2400\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 2,4\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$	21,5 25,0 26,5			mJ mJ mJ
短絡電流 SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CE\text{max}} = V_{CES} - L_{SCE} \cdot di/dt$	$t_P \leq 8\ \mu\text{s}, T_{vj} = 25^{\circ}\text{C}$ $t_P \leq 6\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	$I_{SC}$	4200 3000			A A
ジャンクション・ケース間熱抵抗 Thermal resistance, junction to case	IGBT部 ( 1素子当り ) / per IGBT		$R_{thJC}$			0,09	K/W
ケース・ヒートシンク間熱抵抗 Thermal resistance, case to heatsink	IGBT部 ( 1素子当り ) / per IGBT $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$	0,028			K/W
動作温度 Temperature under switching conditions			$T_{vj\text{op}}$	-40		150	$^{\circ}\text{C}$

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**Diode、インバータ / Diode, Inverter**  
**最大定格 / Maximum Rated Values**

ピーク繰返し逆電圧 Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	600	V
連続DC電流 Continuous DC forward current		$I_F$	600	A
ピーク繰返し順電流 Repetitive peak forward current	$t_P = 1\text{ ms}$	$I_{FRM}$	1200	A
電流二乗時間積 $I^2t$ - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	18000 17000	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$

**電気的特性 / Characteristic Values**

			min.	typ.	max.	
順電圧 Forward voltage	$I_F = 600\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 600\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 600\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1,55 1,50 1,45	1,95	V V V
ピーク逆回復電流 Peak reverse recovery current	$I_F = 600\text{ A}, -di_F/dt = 6000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	205 300 330		A A A
逆回復電荷量 Recovered charge	$I_F = 600\text{ A}, -di_F/dt = 6000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	17,0 36,0 42,0		$\mu\text{C}$ $\mu\text{C}$ $\mu\text{C}$
逆回復損失 Reverse recovery energy	$I_F = 600\text{ A}, -di_F/dt = 6000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	4,00 9,30 10,5		mJ mJ mJ
ジャンクション・ケース間熱抵抗 Thermal resistance, junction to case	/Diode ( 1 素子当り ) / per diode		$R_{thJC}$		0,15	K/W
ケース・ヒートシンク間熱抵抗 Thermal resistance, case to heatsink	/Diode ( 1 素子当り ) / per diode $\lambda_{Paste} = 1\text{ W}/(\text{m}\cdot\text{K}) / \lambda_{grease} = 1\text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$	0,05		K/W
動作温度 Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

**NTC-サーミスタ / NTC-Thermistor**

**電気的特性 / Characteristic Values**

			min.	typ.	max.	
定格抵抗値 Rated resistance	$T_C = 25^{\circ}\text{C}$		$R_{25}$	5,00		k $\Omega$
R100の偏差 Deviation of R100	$T_C = 100^{\circ}\text{C}, R_{100} = 493\ \Omega$		$\Delta R/R$	-5	5	%
損失 Power dissipation	$T_C = 25^{\circ}\text{C}$		$P_{25}$		20,0	mW
B-定数 B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/50}$	3375		K
B-定数 B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/80}$	3411		K
B-定数 B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/100}$	3433		K

適切なアプリケーションノートによる仕様  
Specification according to the valid application note.

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モジュール / Module

絶縁耐圧 Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V <sub>ISOL</sub>	2,5		kV
ベースプレート材質 Material of module baseplate			Cu		
内部絶縁 Internal isolation	基礎絶縁 (クラス1, IEC 61140) basic insulation (class 1, IEC 61140)		Al <sub>2</sub> O <sub>3</sub>		
沿面距離 Creepage distance	連絡方法 - ヒートシンク / terminal to heatsink 連絡方法 - 連絡方法 / terminal to terminal		14,5 13,0		mm
空間距離 Clearance	連絡方法 - ヒートシンク / terminal to heatsink 連絡方法 - 連絡方法 / terminal to terminal		12,5 10,0		mm
相対トラッキング指数 Comperative tracking index		CTI	> 200		
			min.	typ.	max.
ケース・ヒートシンク間熱抵抗 Thermal resistance, case to heatsink	/モジュール / per module $\lambda_{\text{Paste}} = 1 \text{ W/(m}\cdot\text{K)} / \lambda_{\text{grease}} = 1 \text{ W/(m}\cdot\text{K)}$	R <sub>thCH</sub>	0,009		K/W
内部インダクタンス Stray inductance module		L <sub>sCE</sub>	20		nH
パワーターミナル・チップ間抵抗 Module lead resistance, terminals - chip	T <sub>C</sub> = 25°C, /スイッチ / per switch	R <sub>CC+EE'</sub>	1,10		mΩ
保存温度 Storage temperature		T <sub>stg</sub>	-40	125	°C
取り付けネジ締め付けトルク Mounting torque for modul mounting	取り付けネジ M5 適切なアプリケーションノートによるマウンティング Screw M5 - Mounting according to valid application note	M	3,00	-	6,00 Nm
主端子ネジ締め付けトルク Terminal connection torque	取り付けネジ M6 適切なアプリケーションノートによるマウンティング Screw M6 - Mounting according to valid application note	M	3,0	-	6,0 Nm
質量 Weight		G	345		g

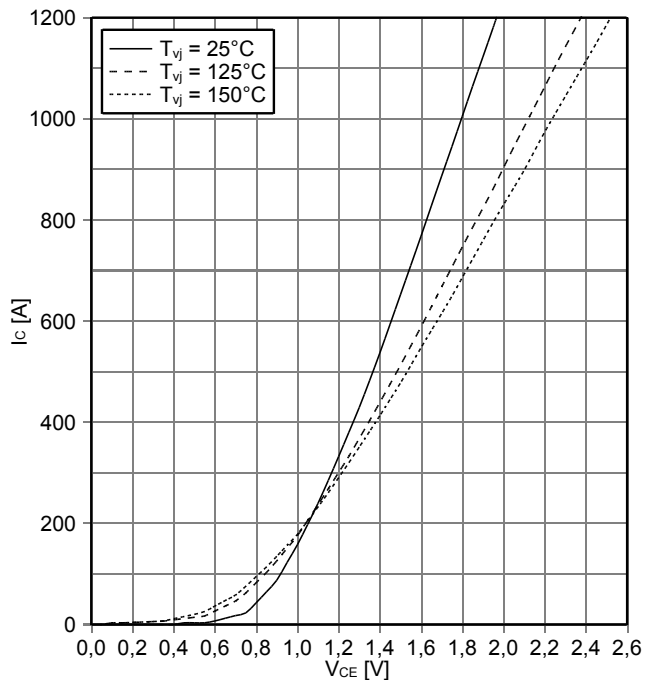
Eon, Eoff, Erec Messungen mit Vce-clamping und zusätzlichem Snubber-Kondensator  
Eon, Eoff, Erec measurements with Vce-clamping and additional snubber-condensator

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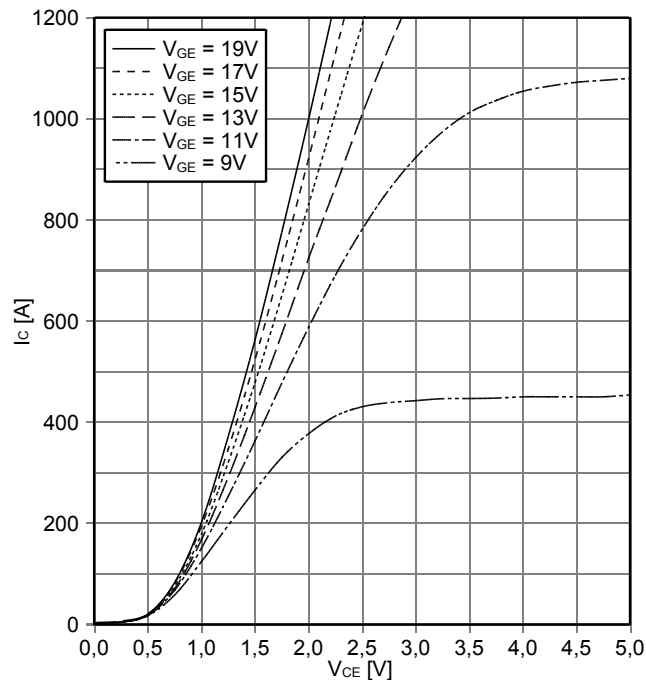
出力特性 IGBT- インバータ (Typical)  
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$   
 $V_{GE} = 15\text{ V}$



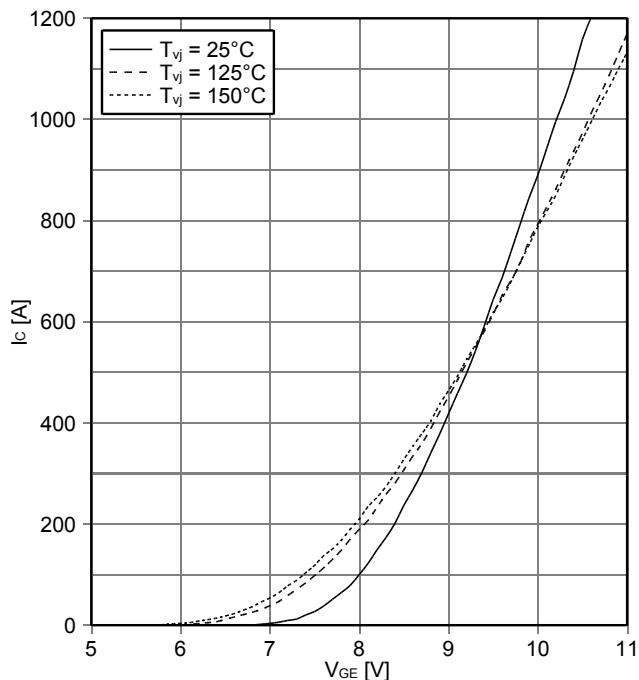
出力特性 IGBT- インバータ (Typical)  
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$   
 $T_{vj} = 150^\circ\text{C}$



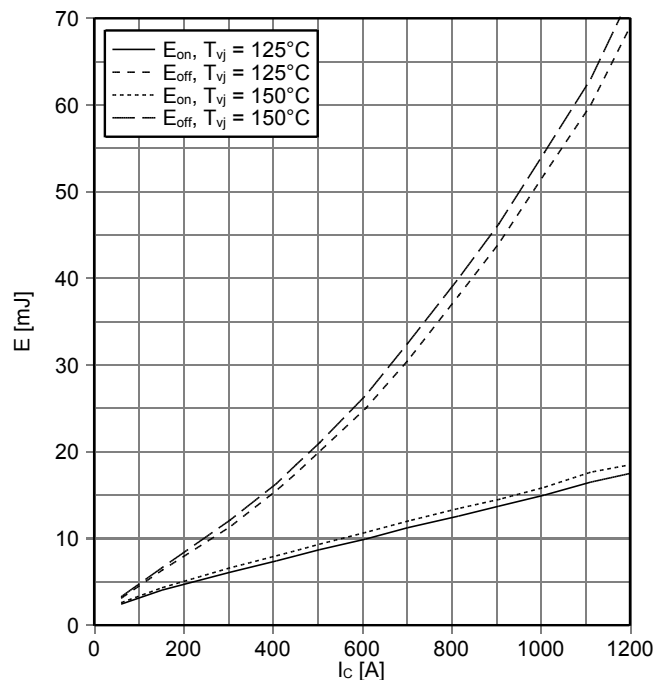
伝達特性 IGBT- インバータ (Typical)  
transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



スイッチング損失 IGBT- インバータ (Typical)  
switching losses IGBT, Inverter (typical)

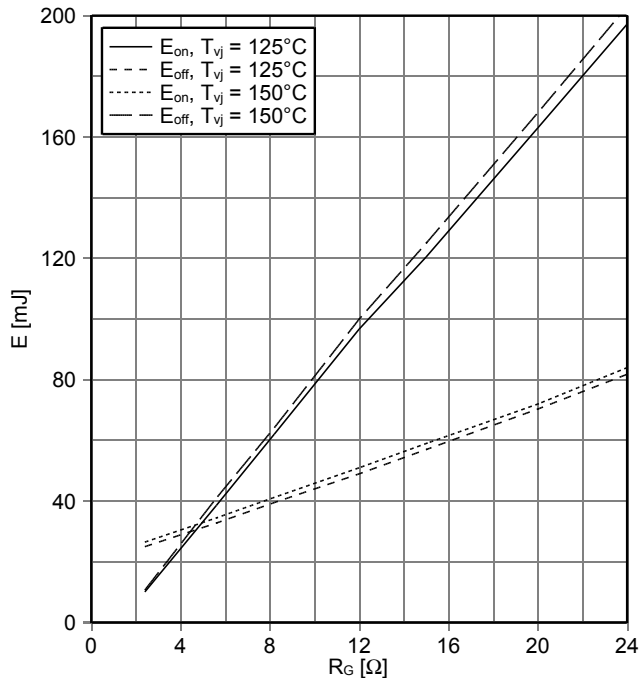
$E_{on} = f(I_C), E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 2.4\ \Omega, R_{Goff} = 2.4\ \Omega, V_{CE} = 300\text{ V}$



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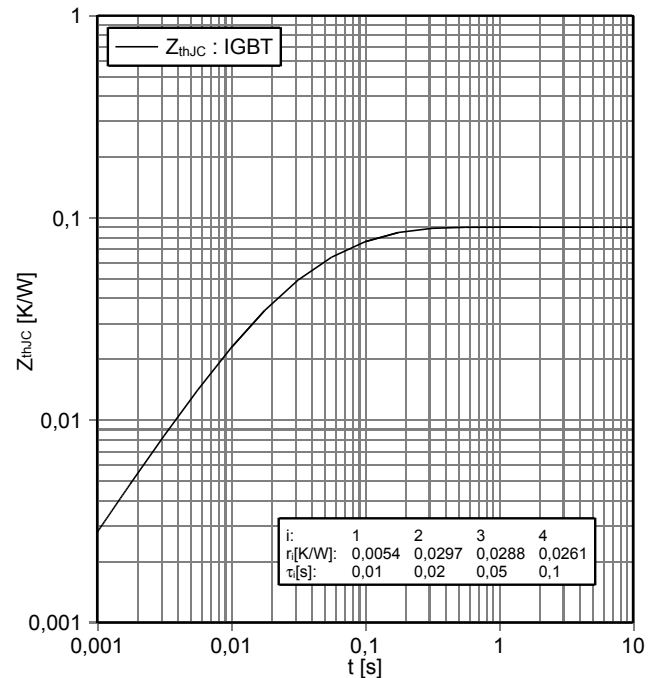
**スイッチング損失 IGBT- インバータ (Typical)**  
**switching losses IGBT, Inverter (typical)**

$E_{on} = f(R_G), E_{off} = f(R_G)$   
 $V_{GE} = \pm 15\text{ V}, I_C = 600\text{ A}, V_{CE} = 300\text{ V}$



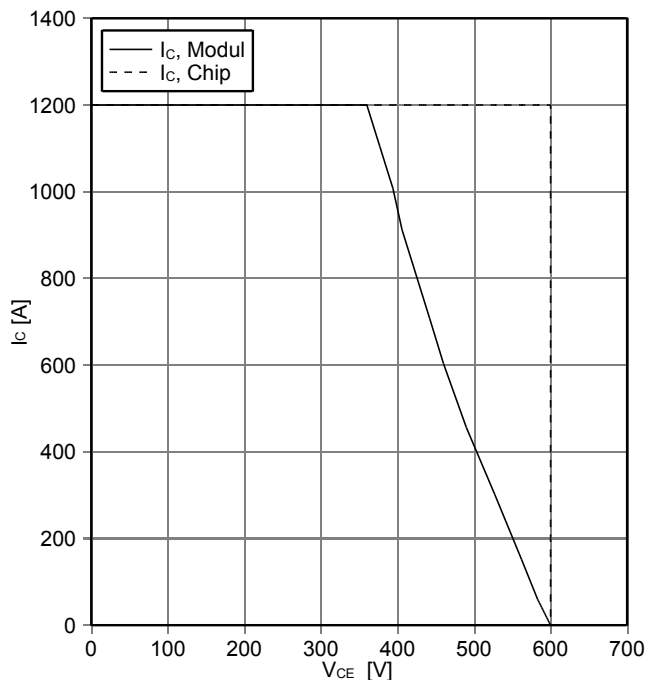
**過渡熱インピーダンス IGBT- インバータ**  
**transient thermal impedance IGBT, Inverter**

$Z_{thJC} = f(t)$



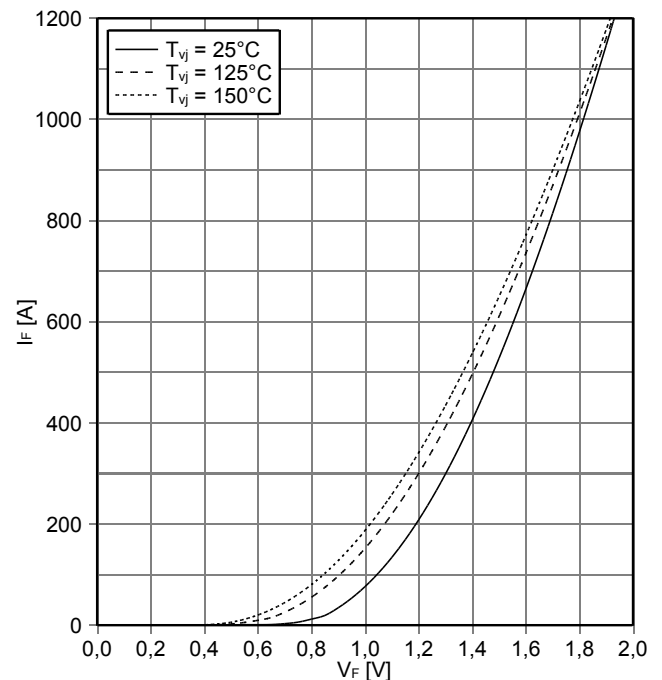
**逆バイアス安全動作領域 IGBT- インバータ ( RBSOA )**  
**reverse bias safe operating area IGBT, Inverter (RBSOA)**

$I_C = f(V_{CE})$   
 $V_{GE} = \pm 15\text{ V}, R_{Goff} = 2.4\ \Omega, T_{vj} = 150^\circ\text{C}$



**順電圧特性 Diode、インバータ ( typical)**  
**forward characteristic of Diode, Inverter (typical)**

$I_F = f(V_F)$

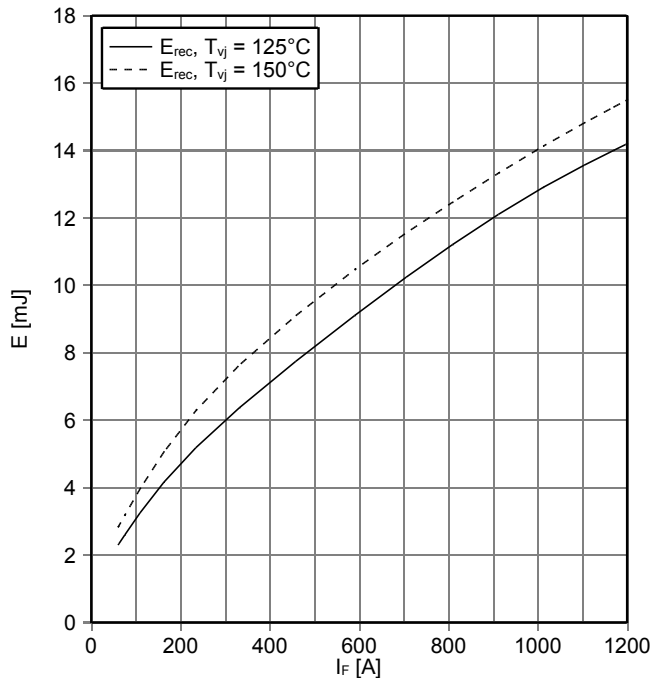


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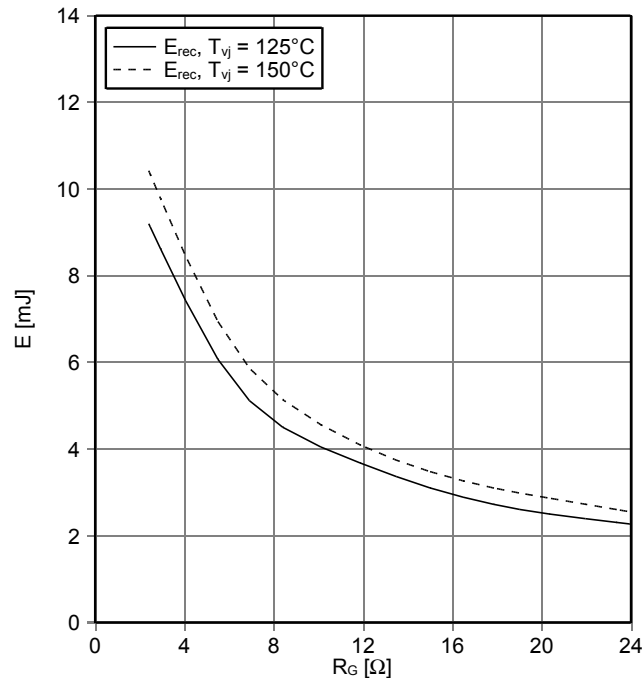
スイッチング損失 Diode、インバータ (Typical)  
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$   
 $R_{Gon} = 2.4 \Omega, V_{CE} = 300 V$



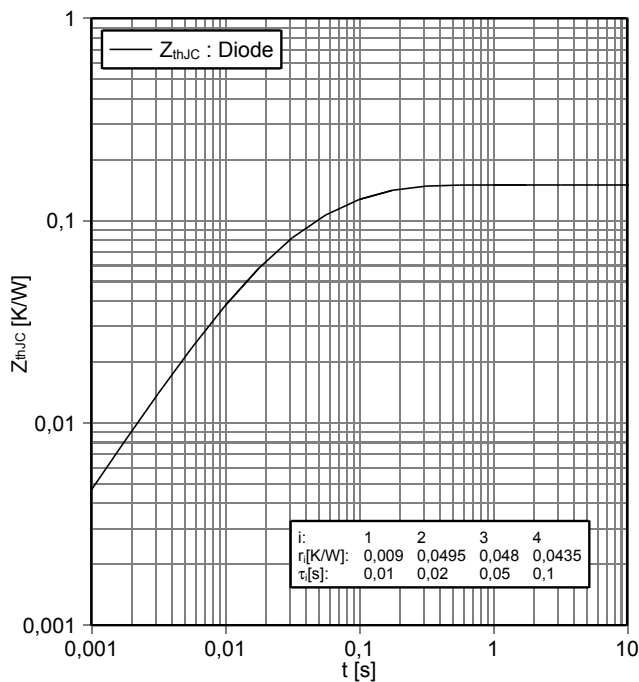
スイッチング損失 Diode、インバータ (Typical)  
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$   
 $I_F = 600 A, V_{CE} = 300 V$



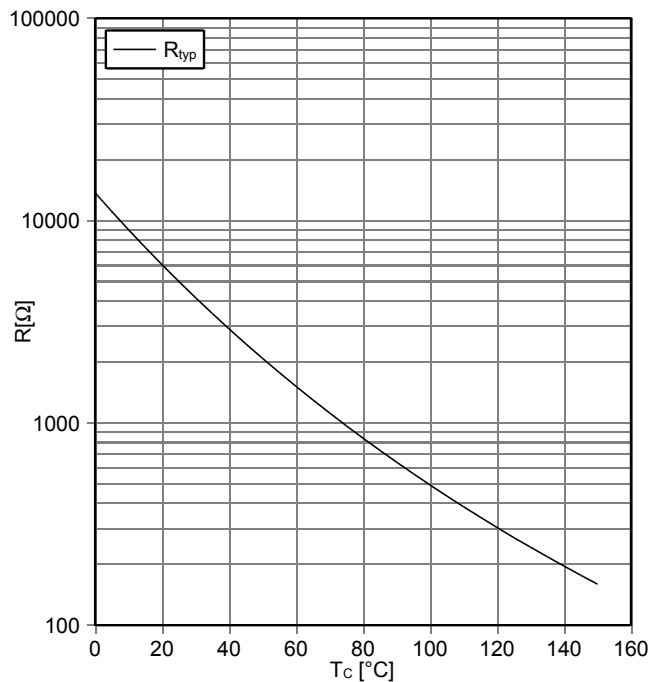
過渡熱インピーダンス Diode、インバータ  
transient thermal impedance Diode, Inverter

$Z_{thJC} = f(t)$



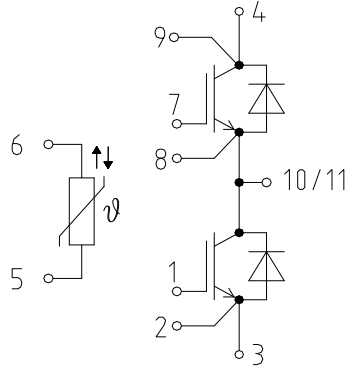
NTC-サーミスタ サーミスタの温度特性  
NTC-Thermistor-temperature characteristic (typical)

$R = f(T)$

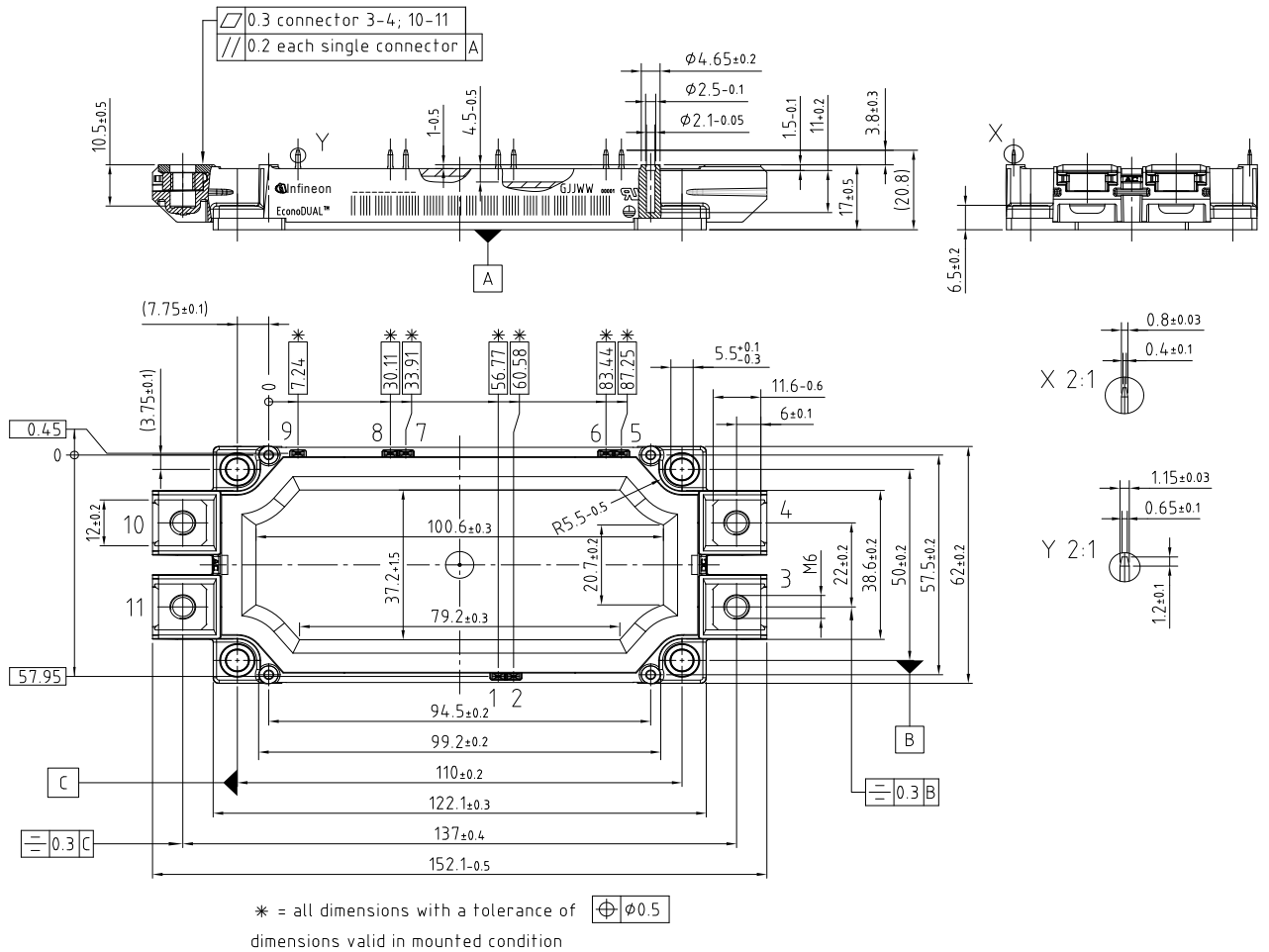


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回路図 / circuit\_diagram\_headline



パッケージ概要 / package outlines



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